

Appl. No. Serial No. 09/714,680
Amdt. dated April 07, 2008
Reply to Office action of November 27, 2007

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. for Reissue No. : 09/714,680
Patent No. : 6,054,198
Applicant : Bunyan *et al.*
Filed : November 16, 2000
Title : Conformal Thermal Interface
Material For Electronic Components

TC/A.U. : 1773
Examiner : S. Ahmed

Docket No. : 2802-257-006

Honorable Commissioner For Patents
Alexandria, VA 22313-1450

DO NOT ENTER: /SA/
04/15/2008

AMENDMENT

In response to the Office action of November 27, 2007, leave to amend the above-identified application as follows is respectfully requested:

Amendments to the Claims are reflected in the listing of the claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.